

IGBT Power Module

1200V / 600A

Preliminary

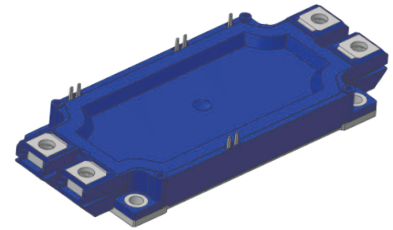
Features

- ◆ Fast Switching Trench / Field Stop IGBT Technology
- ◆ Low Switching Losses
- ◆ Super Fast Diodes
- ◆ High Short Circuit Capability

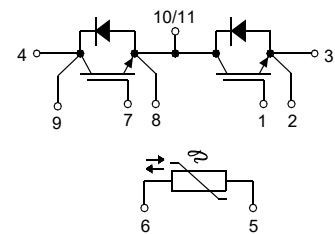
Applications

- ◆ Welder / Power Supply
- ◆ UPS / Inverter
- ◆ Industrial Motor Drive

HDA-15262



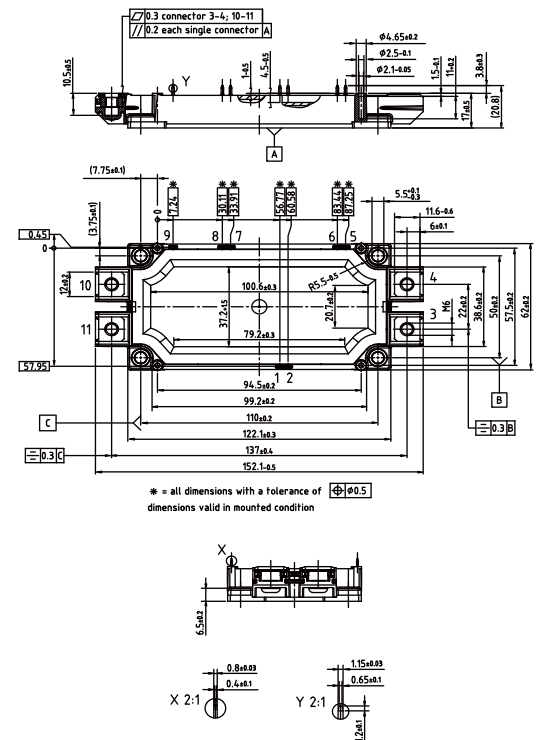
Circuit Diagram Headline



Maximum Ratings (T_C=25°C)

Item	Symbol	Rated Value	Unit
Collector-Emitter Voltage	T _{VJ} = 25°C	V _{CES}	1200 V
Gate-Emitter Peak Voltage		V _{GES}	±20 V
Continuous DC Collector Current	T _C = 100°C	I _{C,nom.}	600 A
Repetitive Peak Collector Current	t _p = 1ms	I _{CRM}	1200 A
Total Power Dissipation		P _{tot}	3380 W
Isolation Voltage	RMS, f=50Hz, t=1min	V _{iso}	2500 V
Continuous DC Forward Current		I _F	600 A
Repetitive Peak Forward Current	t _p = 1ms	I _{FRM}	1200 A
Temperature under switching conditions		T _{VJ op}	-40 ~ +150 °C
Storage Temperature		T _{stg}	-40 ~ +125 °C
Mounting Torque	Module Base to Heatsink (M5)	3~6	N.m
	Busbar to Terminal (M6)	3~6	

Package Outlines



Dimensions in mm (1 mm = 0.0394")

■ Electrical Characteristics ($T_{vj} = 25^{\circ}\text{C}$)

Characteristics	Symbol	Test Conditions	Min.	Typ.	Max.	Unit
Collector-emitter saturation voltage	$V_{CE\text{ sat}}$	$I_C = 600\text{A}, V_{GE} = 15\text{V}$ $T_{vj} = 25^{\circ}\text{C}$ $I_C = 600\text{A}, V_{GE} = 15\text{V}$ $T_{vj} = 125^{\circ}\text{C}$		1.75 2.0	2.1	V
Gate threshold voltage	$V_{GE\text{ th}}$	$I_C = 11.5\text{mA}, V_{CE} = V_{GE}, T_{vj} = 25^{\circ}\text{C}$	5.5	6.0	6.6	V
Gate charge	Q_G	$I_C = 600\text{A}, V_{CE} = 600\text{V}, V_{GE} = 15\text{V}$		2287		nC
Internal gate resistor	$R_{G\text{ int}}$	$T_{vj} = 25^{\circ}\text{C}$		1.07		Ω
Input capacitance	C_{ies}	$f = 100\text{KHz}, T_{vj} = 25^{\circ}\text{C}, V_{CE} = 25\text{V}, V_{GE} = 0\text{V}$		30		nF
Output capacitance	C_{oes}	$f = 100\text{KHz}, T_{vj} = 25^{\circ}\text{C}, V_{CE} = 25\text{V}, V_{GE} = 0\text{V}$		2.5		nF
Reverse transfer capacitance	C_{res}	$f = 100\text{KHz}, T_{vj} = 25^{\circ}\text{C}, V_{CE} = 25\text{V}, V_{GE} = 0\text{V}$		15.1		nF
Collector-emitter cut-off current	I_{CES}	$V_{CE} = 1200\text{V}, V_{GE} = 0\text{V}, T_{vj} = 25^{\circ}\text{C}$			1	mA
Gate-emitter leakage current	I_{GES}	$V_{CE} = 0\text{V}, V_{GE} = 20\text{V}, T_{vj} = 25^{\circ}\text{C}$			100	nA
Turn-on delay time, inductive load	$t_{d\text{ on}}$	$I_C = 600\text{A}, V_{CE} = 600\text{V}$ $T_{vj} = 25^{\circ}\text{C}$		356		ns
		$V_{GE} = \pm 15\text{V}$ $T_{vj} = 125^{\circ}\text{C}$		366		
		$R_{G(\text{on})} = 0.5\Omega, R_{G(\text{off})} = 0.5\Omega$ $T_{vj} = 150^{\circ}\text{C}$		360		
Rise time, inductive load	t_r	$I_C = 600\text{A}, V_{CE} = 600\text{V}$ $T_{vj} = 25^{\circ}\text{C}$		100		ns
		$V_{GE} = \pm 15\text{V}$ $T_{vj} = 125^{\circ}\text{C}$		108		
		$R_{G(\text{on})} = 0.5\Omega, R_{G(\text{off})} = 0.5\Omega$ $T_{vj} = 150^{\circ}\text{C}$		132		
Turn-off delay time, inductive load	$t_{d\text{ off}}$	$I_C = 600\text{A}, V_{CE} = 600\text{V}$ $T_{vj} = 25^{\circ}\text{C}$		449		ns
		$V_{GE} = \pm 15\text{V}$ $T_{vj} = 125^{\circ}\text{C}$		492		
		$R_{G(\text{on})} = 0.5\Omega, R_{G(\text{off})} = 0.5\Omega$ $T_{vj} = 150^{\circ}\text{C}$		508		
Fall time, inductive load	t_f	$I_C = 600\text{A}, V_{CE} = 600\text{V}$ $T_{vj} = 25^{\circ}\text{C}$		49		ns
		$V_{GE} = \pm 15\text{V}$ $T_{vj} = 125^{\circ}\text{C}$		74		
		$R_{G(\text{on})} = 0.5\Omega, R_{G(\text{off})} = 0.5\Omega$ $T_{vj} = 150^{\circ}\text{C}$		76		
Turn-on energy loss per pulse	E_{on}	$I_C = 600\text{A}, V_{CE} = 600\text{V}$ $T_{vj} = 25^{\circ}\text{C}$		27		mJ
		$V_{GE} = \pm 15\text{V},$ $T_{vj} = 125^{\circ}\text{C}$		64		
		$R_{G(\text{on})} = 0.5\Omega, R_{G(\text{off})} = 0.5\Omega$ $T_{vj} = 150^{\circ}\text{C}$		74		
Turn-off energy loss per pulse	E_{off}	$I_C = 600\text{A}, V_{CE} = 600\text{V}$ $T_{vj} = 25^{\circ}\text{C}$		47		mJ
		$V_{GE} = \pm 15\text{V}$ $T_{vj} = 125^{\circ}\text{C}$		56		
		$R_{G(\text{on})} = 0.5\Omega, R_{G(\text{off})} = 0.5\Omega$ $T_{vj} = 150^{\circ}\text{C}$		59		
SC data	I_{SC}	$V_{GE} \leq 15\text{V}, V_{CC} = 800\text{V}$ $V_{CE\text{ max}} = V_{CES} - L_{s\text{ CE}} \cdot di/dt$ $T_{vj} = 25^{\circ}\text{C}$		$t_p \leq 10\mu\text{s},$ $T_{vj} = 150^{\circ}\text{C}$	2400	A
Thermal resistance, junction to case	$R_{th\text{ JC}}$	per IGBT			0.037	$^{\circ}\text{C/W}$
Thermal resistance, case to heatsink	$R_{th\text{ CH}}$	per IGBT		0.035		$^{\circ}\text{C/W}$
External gate resistance	$R_{G\text{ ext}}$	$T_{vj} = 25^{\circ}\text{C}$	0.5			Ω

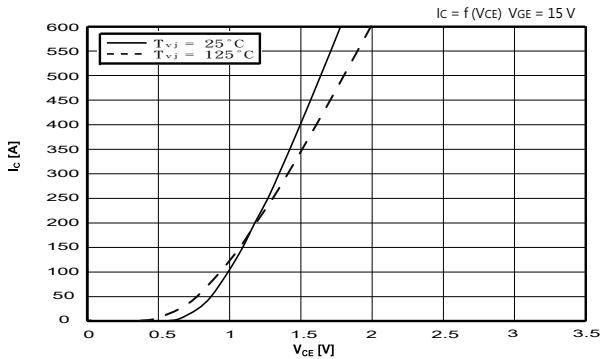
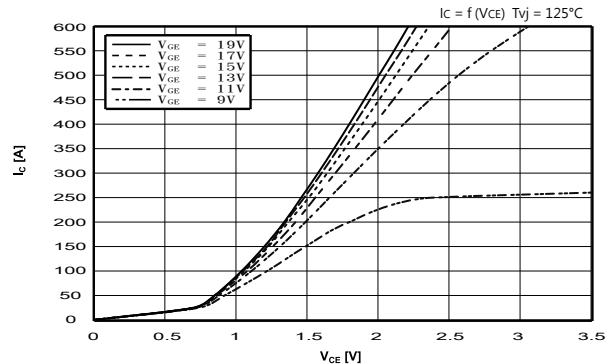
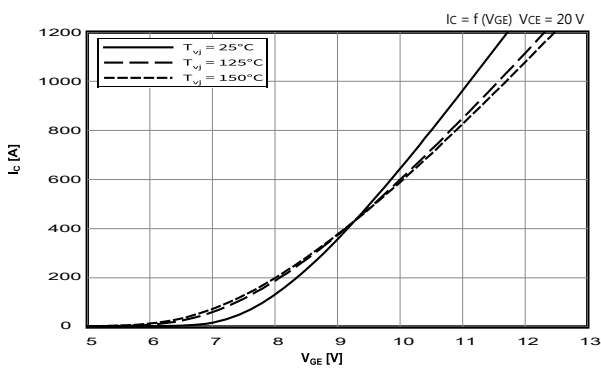
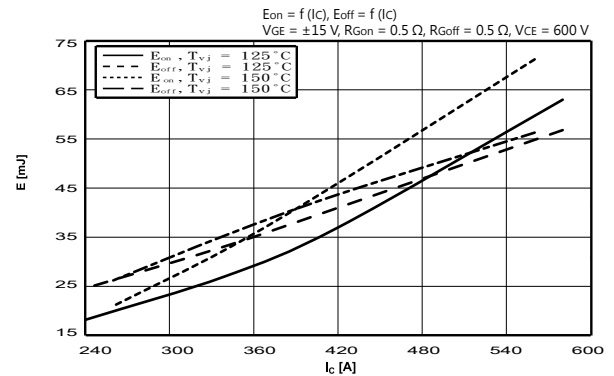
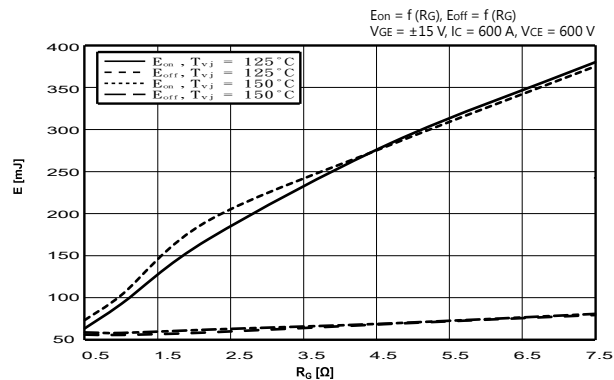
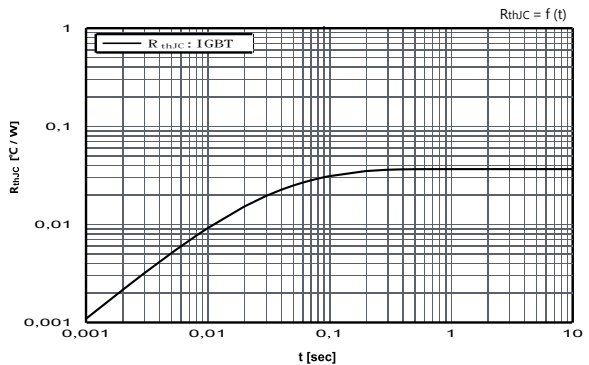
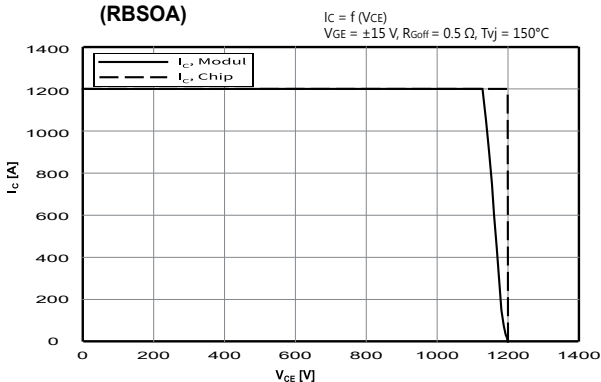
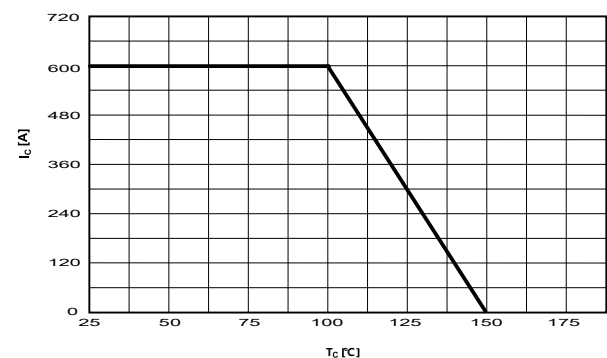
■ Diode Ratings & Characteristics

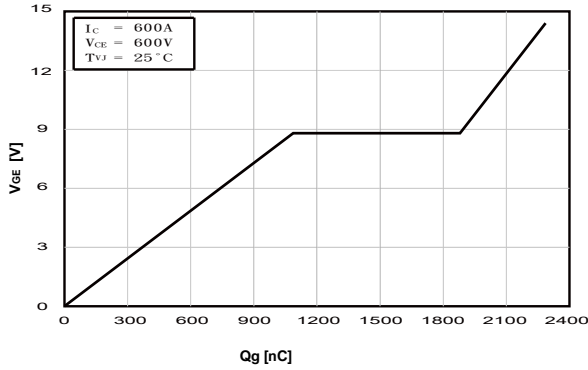
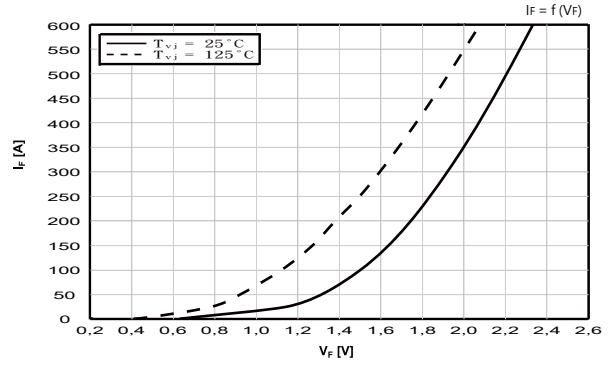
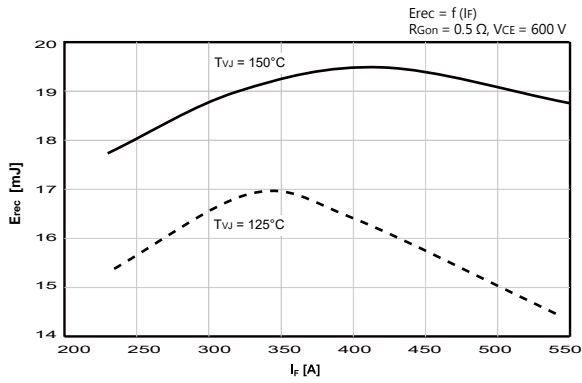
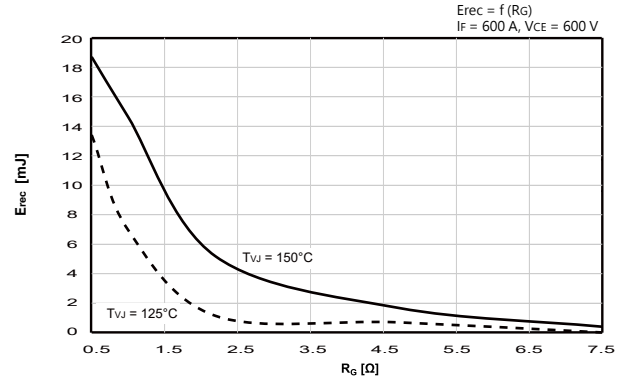
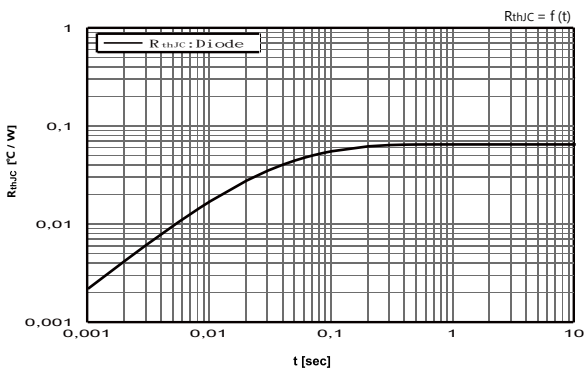
Characteristics	Symbol	Test Conditions	Value	Unit
Repetitive peak reverse voltage	V_{RRM}	$T_{vj} = 25^{\circ}\text{C}$	1200	V
Continuous DC forward current	I_F		600	A
Repetitive peak forward current	I_{FRM}	$t_p = 1\text{ms}$	1200	A
I^2t - value	I^2t	$V_R = 0\text{V}, t_p = 10\text{ms}, T_{vj} = 125^{\circ}\text{C}$	40000	A ² s
		$V_R = 0\text{V}, t_p = 10\text{ms}, T_{vj} = 150^{\circ}\text{C}$	37500	

Characteristics	Symbol	Test Conditions	Min.	Typ.	Max.	Unit
Forward voltage	V_F	$I_F = 600\text{A}, V_{GE} = 0\text{V}$ $T_{vj} = 25^{\circ}\text{C}$		2.3	2.6	V
		$I_F = 600\text{A}, V_{GE} = 0\text{V}$ $T_{vj} = 125^{\circ}\text{C}$		2.0		
Peak reverse recovery current	I_{RRM}	$I_F = 600\text{A}, -di_F/dt = 5000\text{ A}/\mu\text{s}$ $T_{vj} = 25^{\circ}\text{C}$		216		A
		$V_R = 600\text{V}$ $T_{vj} = 125^{\circ}\text{C}$		336		
		$V_{GE} = \pm 15\text{V}$ $T_{vj} = 150^{\circ}\text{C}$		344		
Recovered charge	Qrr	$I_F = 600\text{A}, -di_F/dt = 5000\text{ A}/\mu\text{s}$ $T_{vj} = 25^{\circ}\text{C}$		19610		nC
		$V_R = 600\text{V}$ $T_{vj} = 125^{\circ}\text{C}$		44870		
		$V_{GE} = \pm 15\text{V}$ $T_{vj} = 150^{\circ}\text{C}$		61250		
Reverse recovery energy	Erec	$I_F = 600\text{A}, -di_F/dt = 5000\text{ A}/\mu\text{s}$ $T_{vj} = 25^{\circ}\text{C}$		8343		uJ
		$V_R = 600\text{V}$ $T_{vj} = 125^{\circ}\text{C}$		13400		
		$V_{GE} = \pm 15\text{V}$ $T_{vj} = 150^{\circ}\text{C}$		18700		
Reverse Recovery Time	Trr	$I_F = 600\text{A}, -di_F/dt = 5000\text{ A}/\mu\text{s}, V_R = 600\text{V}, V_{GE} = \pm 15\text{V}, T_{vj} = 25^{\circ}\text{C}$		183		ns
Thermal resistance, junction to case	R_{thJC}	per diode			0.065	$^{\circ}\text{C}/\text{W}$
Thermal resistance, case to heatsink	R_{thCH}	per diode		0.039		$^{\circ}\text{C}/\text{W}$
Temperature under switching conditions	$T_{vj\text{ op}}$		-40		150	$^{\circ}\text{C}$

■ Package

Parameter	Symbol	Test Conditions	Value	Unit
Creepage distance	$d_{\text{Creep nom}}$	terminal to baseplate, nom.	> 15	mm
Creepage distance	$d_{\text{Creep min}}$	terminal to baseplate, min.	14.7	mm
Creepage distance	$d_{\text{Creep nom}}$	terminal to terminal, nom.	> 19.3	mm
Creepage distance	$d_{\text{Creep min}}$	terminal to terminal, min.	19.3	mm
Clearance	$d_{\text{Clear nom}}$	terminal to baseplate, nom.	> 12.5	mm
Clearance	$d_{\text{Clear min}}$	terminal to baseplate, min.	12.5	mm
Clearance	$d_{\text{Clear nom}}$	terminal to terminal, nom.	> 10	mm
Clearance	$d_{\text{Clear min}}$	terminal to terminal, min.	9.6	mm

Typical Characteristics
Preliminary Data
Fig.1 Output characteristic IGBT, Inverter (typical)

Fig.2 Output characteristic IGBT, Inverter (typical)

Fig.3 Transfer characteristic IGBT, Inverter (typical)

Fig.4 Switching losses IGBT, Inverter (typical)

Fig.5 Switching losses IGBT, Inverter (typical)

Fig.6 Transient thermal impedance IGBT, Inverter

Fig.7 Reverse bias safe operating area IGBT, Inverter (RBSOA)

Fig.8 Output characteristic IGBT, Inverter (typical)


Typical Characteristics
Preliminary Data
Fig.9 Gate Charge Characteristics(typical)

Fig.10 Forward characteristic of Diode, Inverter (typical)

Fig.11 Switching losses Diode, Inverter (typical)

Fig.12 Switching losses Diode, Inverter (typical)

Fig.13 Transient thermal impedance Diode, Inverter


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